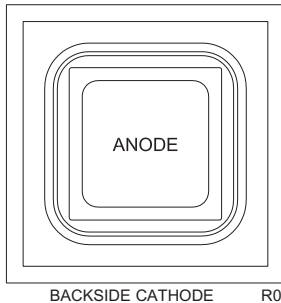


The CPZ58X-BZX55C3V3 thru CPZ58X-BZX55C15 are silicon Zener diodes ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	13 x 13 MILS
Die Thickness	5.5 MILS
Anode Bonding Pad Size	5.9 x 5.9 MILS
Top Side Metalization	AlSiCu – 35,000Å
Back Side Metalization	AuAs – 12,000Å
Scribe Alley Width	1.69 MILS
Wafer Diameter	6 INCHES
Gross Die Per Wafer	142,858

MAXIMUM RATINGS:

Operating and Storage Junction Temperature

SYMBOL

T_J, T_{stg}

-65 to +150

UNITS

°C

ELECTRICAL CHARACTERISTICS: ($T_A=25^\circ\text{C}$) $V_F=1.0\text{V MAX @ } I_F=100\text{mA}$ (for all types)

Type	Zener Voltage $V_Z @ I_{ZT}$			Test Current I_{ZT}	Maximum Zener Impedance			Maximum Reverse Current		Maximum Zener Current I_{ZM}	Maximum Temperature Coefficient ΘV_Z
	MIN	NOM	MAX		$Z_{ZT} @ I_{ZT}$	$Z_{ZK} @ I_{ZK}$	$I_R @ V_R$	I_{ZM}			
	V	V	V		mA	Ω	Ω	mA	μA		
CPZ58X-BZX55C3V3	3.1	3.3	3.5	5.0	85	600	1.0	2.0	1.0	115	-0.060
CPZ58X-BZX55C3V6	3.4	3.6	3.8	5.0	85	600	1.0	2.0	1.0	105	-0.055
CPZ58X-BZX55C3V9	3.7	3.9	4.1	5.0	85	600	1.0	2.0	1.0	95	-0.050
CPZ58X-BZX55C4V3	4.0	4.3	4.6	5.0	75	600	1.0	1.0	1.0	90	-0.040
CPZ58X-BZX55C4V7	4.4	4.7	5.0	5.0	60	600	1.0	0.5	1.0	85	-0.020
CPZ58X-BZX55C5V1	4.8	5.1	5.4	5.0	35	550	1.0	0.1	1.0	80	+0.010
CPZ58X-BZX55C5V6	5.2	5.6	6.0	5.0	25	450	1.0	0.1	1.0	70	+0.025
CPZ58X-BZX55C6V2	5.8	6.2	6.6	5.0	10	200	1.0	0.1	2.0	64	+0.032
CPZ58X-BZX55C6V8	6.4	6.8	7.2	5.0	8.0	150	1.0	0.1	3.0	58	+0.040
CPZ58X-BZX55C7V5	7.0	7.5	7.9	5.0	7.0	50	1.0	0.1	5.0	53	+0.045
CPZ58X-BZX55C8V2	7.7	8.2	8.7	5.0	7.0	50	1.0	0.1	6.2	47	+0.048
CPZ58X-BZX55C9V1	8.5	9.1	9.6	5.0	10	50	1.0	0.1	6.8	43	+0.050
CPZ58X-BZX55C10	9.4	10.0	10.6	5.0	15	70	1.0	0.1	7.5	40	+0.055
CPZ58X-BZX55C11	10.4	11.0	11.6	5.0	20	70	1.0	0.1	8.2	36	+0.060
CPZ58X-BZX55C12	11.4	12	12.7	5.0	20	90	1.0	0.1	9.1	32	+0.065

**CPZ58X-BZX55C3V3 THRU
CPZ58X-BZX55C15
Zener Diode Die
500mW, 3.3 THRU 15 VOLT**

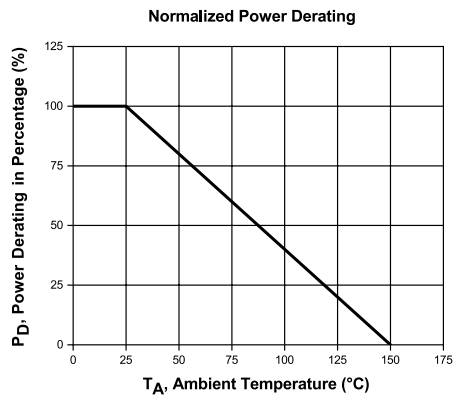
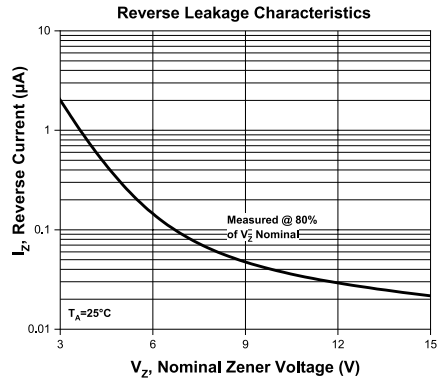
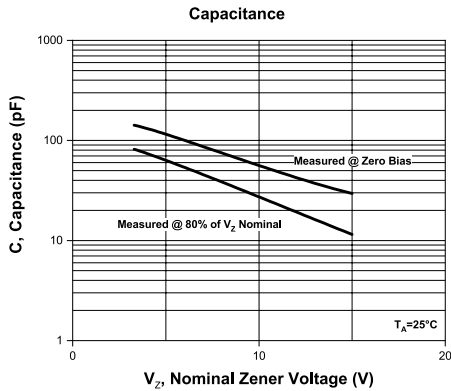
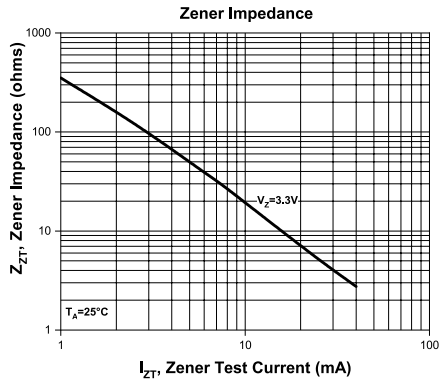
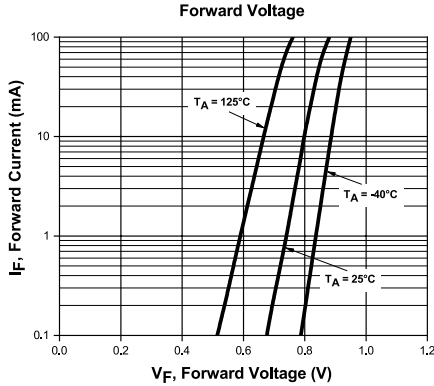


ELECTRICAL CHARACTERISTICS - Continued: ($T_A=25^{\circ}\text{C}$) $V_F=1.0\text{V MAX @ } I_F=100\text{mA}$ (for all types)

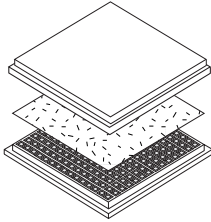
Type	Zener Voltage $V_Z @ I_{ZT}$			Test Current I_{ZT}	Maximum Zener Impedance			Maximum Reverse Current		Maximum Zener Current I_{ZM}	Maximum Temperature Coefficient $\ominus V_Z$
	MIN	NOM	MAX		$Z_{ZT} @ I_{ZT}$	$Z_{ZK} @ I_{ZK}$		$I_R @ V_R$			
	V	V	V		mA	Ω	Ω	mA	μA		
CPZ58X-BZX55C13	12.4	13	14.1	5.0	26	110	1.0	0.1	10	29	+0.070
CPZ58X-BZX55C15	13.8	15	15.6	5.0	30	110	1.0	0.1	11	27	+0.070

CPZ58X-BZX55C3V3 THRU CPZ58X-BZX55C15

Typical Electrical Characteristics



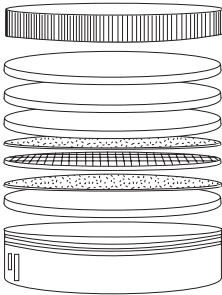
BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

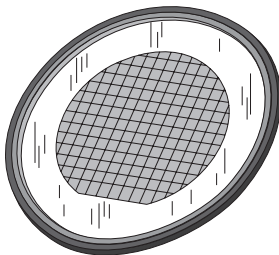
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

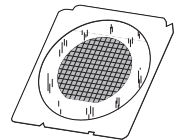
WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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